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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)				Application Number	10/802,885
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				Filing Date	March 18, 2004
				First Named Inventor	Haruhiko MURATA
				Art Unit	Not Yet Assigned
				Examiner Name	Not Yet Assigned
Sheet 1 of 1				Attorney Docket Number	Q80543

U.S. PATENT DOCUMENTS

Examiner Initials*	Cite No. ¹	Document Number		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document
		Number	Kind Code ² (if known)		
[Signature]		US 5,364,460		11-15-1994	MORIMOTO et al.
		US 2001/0053562	A1	12-20-2001	IBA et al.
		US 6,495,211	B2	12-17-2002	IBA et al.
		US 2003/0096064	A1	05-22-2003	SUDA et al.
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FOREIGN PATENT DOCUMENTS

Examiner Initials*	Cite No. ¹	Foreign Patent Document			Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Translation ⁶
		Country Code ³	Number ⁴	Kind Code ⁵ (if known)			
[Signature]		JP	6-330336		11-29-1994	C UYEMURA & CO LTD	Abstract
		JP	2002-4098		01-09-2002	NGK SPARK PLUG CO LTD	Abstract
		JP	2003-13248		01-15-2003	LEARONAL JAPAN INC	Abstract

NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city, and/or country where published.	Translation ⁶
[Signature]		Hisaaki TAKAO et al.; "Development of Highly Reliable Sn-Ag Lead-Free Solder Alloy"; Vol. 35; No. 2; June 2000; pp. 39-46	Abstract
[Signature]		Masayoshi DATE et al.; "Evaluation of Lead-Free Solder Balls Produced By Uniform Droplet Spray Method"; Vol. 18; 2002; pp. 43-48	Abstract

Examiner Signature	<i>Thomas Magee</i>	Date Considered	9/9/05
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹ Applicant's unique citation designation number (optional). ² See Kind Codes of USPTO Patent Documents at www.uspto.gov, MPEP 901.04 or in the comment box of this document. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST. 3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶ Applicant is to indicate here if English language Translation is attached.